ON Semiconductor

PRODUCT/PROCESS CHANGE NOTIFICATION #16617

Generic Copy

Issue Date: 25-March-2011

TITLE: Discontinuance of ASEK SnPb Plating Line and Utilize External Plating House in Taiwan

PROPOSED FIRST SHIP DATE: 25 June 2011 (See Note Below)

AFFECTED CHANGE CATEGORY(S): Assembly Site Transfer – Plating Process Only

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: Available
Contact your local ON Semiconductor Sales Office

NOTIFICATION TYPE:

Termination Finish Site Change

Notification is issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

ASE Kaohsiung will phase out their internal SnPb plating process for ASE GP (Green Product) policy and will utilize their qualified external Plating house for products with SnPb plating requirement. The external plating house is Advanplating Technology Co. Ltd located in Taiwan.

Note: This change will actually occur earlier than the proposed first ship date identified in this PCN due to supplier's manufacturing circumstances.

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QUALIFICATION DATA:

Summary of Results

Based on the quality index for plating thickness, plating composition, appearance of product, and solder-ability, all data showed positive results; that is, Advanplating Sn-Pb plating quality can reach good plating quality performance.

AdvanPlating Technology quality performance of SnPb is no different from ASE Kaoshiung SnPb plating.

Quality Characteristics Summary

Quality Characteristic	Ideal Target	ASEK Mean	ASEK Std Dev	AP Mean	AP Std Dev	Result
Plating thickness	300 - 800 μ-inch	503.1	31.7	496.6	32.1	SE
Plating Composition	80 - 90% Sn	84.3	0.42	87.6	0.34	SE
Solder-ability test	Solder coverage > 95%	0 ppm (< 95%)	N/A	0 ppm (< 95%)	N/A	SE
Appearance of product	Follow ASE SPEC. 62-31-5130-0004 item 6.8	0 ppm	N/A	0 ppm	N/A	SE

Legend:
SE – Statistically Equivalent

CHANGED PART IDENTIFICATION:

No change in ONSEMI Part number

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List of affected General Parts:

PART
11564-507-XTD
11564-507-XTP

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List of affected Customer Specific Parts:

PART
06809-519-XTD
0CZAA-001-XTD
0FHOA-001-XTD
0GMAC-001-XTD
0I278-001-XTD
11133-505-XTD
11311-503-XTD
11717-001-XTD
11894-501-XTD
11933-501-XTD
12041-001-XTD
12095-801-XTD
12095-801-XTP
12169-001-XTD
12194-501-XTD
13505-504-XTD
13505-512-XTD
13657-501-XTD
13873-501-XTD
13879-001-XTD
14230-501-XTD
14286-501-XTD
14287-501-XTD
14298-501-XTD
15004-023-XTD
15007-020-XTD
15007-518-XTD
15016-506-XTD
15019-001-XTD
15025-509-XTD
20468-006-XTD
61701-001-XTD
61731-001-XTD
61787-001-XTD
61787-001-XTP
61788-001-XTD
61788-001-XTP
61789-001-XTD
62059-001-XTD
62088-001-XTD
62145-001-XTD
62168-001-XTD
62177-001-XTD
62177-001-XTP
62239-001-XTP
62280-001-XTD